



TIA™800FG Series products are mostly used for bonding heat dissipation fins, microprocessors and other power consumption semiconductors. This type of adhesive tape possesses ultimate bonding strength with low thermal impedance, with which in effect can be able to replace the method of lubricating grease and mechanical fixing.

Feature

- » Thermal Conductivity **0.8W/mK**
- » High performance, thermally conductive acrylic adhesive.
- » High bond strength to a variety of surfaces Double sided pressure sensitive adhesive tape.

Application

- » Mount heat sink onto BGA graphic processor or drive processor.
- » Mount heat spreader onto power converter PCB or onto motor control.
- » Can be used instead of heat cure adhesive, screw mounting or clip mounting.



Typical Properties of TIA™800FG series

Typical Properties	TIA805FG	TIA806FG	TIA808FG	TIA810FG	TIA812FG	TIA815FG	TIA820FG	Test Method
Color	White							Visual
Adhesive Type	Acrylic Adhesive							*****
Backing Type	The glass fiber							*****
Continuous Use Temp	-45 °C to 120 °C							*****
Thickness	0.005" 0.127mm	0.006" 0.152mm	0.008" 0.203mm	0.010" 0.254mm	0.012" 0.304mm	0.015" 0.381mm	0.020" 0.508mm	ASTM D374
Voltage Breakdown	> 2500 Vac	> 3000 Vac	> 3500 Vac	> 4000 Vac	> 4200 Vac	> 4500 Vac	> 5000 Vac	ASTM D149
Thermal Conductivity	0.8 W/mK							ASTM D5470
180° Peel Adhesion	> 1000 g/inch (Steel, Immediate)							PSTC-1
180° Peel Adhesion	> 1200 g/inch (Steel after 24 hrs)							PSTC-1
Holding Power (25 °C/Hours)	> 48 Hours							PSTC-7
Holding Power (80 °C/Hours)	> 48 Hours							PSTC-7

Standard Thicknesses:

0.005"(0.127mm) 0.006"(0.152mm) 0.008"(0.203mm) 0.010"(0.254mm)
0.012"(0.304mm) 0.015"(0.381mm) 0.020"(0.508mm)

Consult the factory alternate thickness.

Standard Sizes:

16" x 100'(406mm x 30.48M) Individual die cut shapes can be supplied.

Reinforcement:

TIA™800FG Series rolls type can add with fiberglass reinforced.



If you want to know our thermal Products, you can visit our website. <http://www.ziitek.com>

Gap Fillers | Pouring sealant | Silicon tape | Thermally Conductive paste | Flake graphite | Thermally Conductive Insulators | Ceramic heat sinks
| Thermally Conductive plastic | Thermally Conductive Adhesive Tapes

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